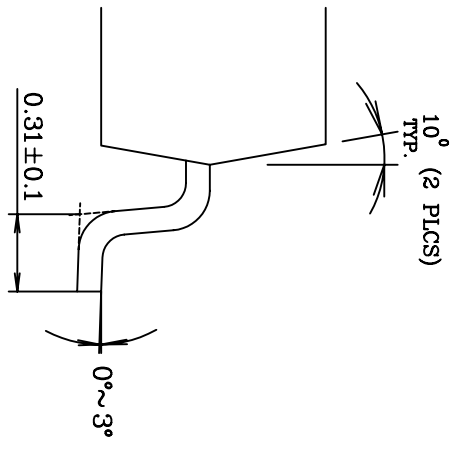
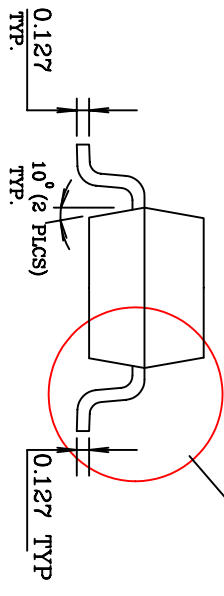
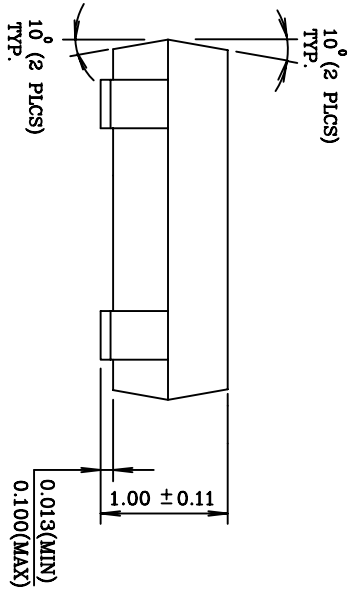


- NOTE:
1. Dimensions and tolerances are as per ANSI Y14.5M, 1982.
 2. Package surface to be mirror finish.
 3. Die is facing up for mold & trim/form.
- △ Dimensions are exclusive of mold flash and gate burr.



COPPER FRAME

Reference to Jeduc Spec # : T0236 Issue G.

REV.	DESCRIPTION	DATE	BY	APPD
0	Original design.	19/05/98	CH TAN	PT
△	Change lead width to 0.360(MIN)to 0.520(MAX) – (was 0.4)	03/06/99	ANDREW	PT
B	Add note NO.4.	15/01/01	ANDREW	PT
C	Note: Metal burr revise to gate burr as per Jeduc spec. Lead width change to 0.37-0.51 (was 0.36-0.52) as per Jeduc spec.	18/01/02	ANDREW	PT

TOLERANCES		DWN: ANDREW	DATE: 18/01/02
REFER TO THE SPECIFICATION ABOVE.		APPD: CH TAN	DATE:
UNIT: MM	SCALE: NTS	APPD: CK TANG	DATE:
SYMBOL		APPD: CW CHAI	DATE:
		APPD: SRI	DATE:
		DWG. NO: SOT3-POC-001	REV.: C
SOT-23 (3L) PACKAGE CASE OUTLINE			
SHEET NO : 1 OF 1.			